ALLIANCE MEMORY MDS REPORT

Part Number :				**AS25F3128MQ-6SIN**				
Part Weight (mg):				**126.99**				
NO.	**Material**	**Supplier**	**Type**	**Purpose**	**Substances**	**CAS No.**	**Weight**	**Wt %**
1	**Molding Compound**	**HYSOL HUAWEI**	**GR710**	**Molding Compound**			**71.005**	**55.91%**
					Silica	60676-86-0		80~90
					Epoxy resin	Trade Secret		5~10
					2,2'-((3,5',5,5'-tetramethyl-(1,1'- biphenyl)-4,4'-diyl)-bis(oxymethylene))-bis-oxirane	85954-11-6		1~5
					3-Trimethoxysilylpropane-1-thiol	4420-74-0		0.1~1
					Carbon black	1333-86-4		0.1~1
2	**leadframe**	**FU**	**A194**	**leadframe**			**49.54**	**39.01%**
					Copper (Cu)	7440-50-8		95.9375
					Iron (Fe)	7439-89-6		2.1~2.6
					Phosphorus (P)	7723-14-0		0.015~0.15
					Zinc (Zn)	7440-66-6		0.05~0.02
					Lead	7439-92-1		0~0.01
					Silver (Ag)	7440-22-4		0.5~2.5
3	**Silver Epoxy**	**Sumitomo**	**1076WA**	**Silver Epoxy**			**0.61**	**0.48%**
					Silver Powder	7440-22-4		70~90
					Epoxy Resin A	9003-36-5		1~5
					Epoxy Resin B	Trade Secret		5~10
					Diluent A	Trade Secret		5~10
					Diluent B	Trade Secret		1~5
					Hardener	Trade Secret		1~5
					Dicyandiamide	461-58-5		0.1~1
					Organic Peroxide			0.1~1
4	**Wire**	**LT**	**AuPd**	**Wire**			**0.029**	**0.02%**
					Copper : Wire	7440-50-8		7.11% ~ 99.18%
					Palladium	7440-05-3		8% ~ 2.7%
					Gold	7440-57-5		0.02% ~ 0.19%
5	**Solder Plating**	**Sinyang**	**Pure Tin**	**Solder Plating**			**2.62**	**2.06%**
					Tin	7440-31-5		99.99
					Other	Trade Secret		0.01
6	**Die**	**XMC**	**Wafer**	**Die**			**3.1860**	**2.51%**
					Silicon	Trade Secret		60.53
						Total	**126.99**	**100%**

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